


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	EMBEDDED PROCESSING/26/15869	
<b>1.3 Title of PCN</b>	STM32H562x, STM32H563x and STM32H573x - product enhancement	
<b>1.4 Product Category</b>	STM32H562x , STM32H563x and STM32H573x	
<b>1.5 Issue date</b>	2026-02-05	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	
<b>2.1.2 Phone</b>	
<b>2.1.3 Email</b>	
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	
<b>2.1.2 Marketing Manager</b>	
<b>2.1.3 Quality Manager</b>	

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles 300 (France)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	Current STM32H562x, STM32H563x and STM32H573 (Revision X) products and System Flash Security Package (SFSP) have limitations as described in Errata Sheet ES0565 - Rev 6 - March 2025	STM32H562x, STM32H563x and STM32H573 (Revision W) products & System Flash Security Package (SFSP) enhancement.  Change of security descriptor located on Bootloader area needed for integration w/ SFSP : - The change of the SFSP descriptor located in Bootloader area has no impact on Bootloader. - The Bootloader binary remains unchanged. - Changes done in SFSP descriptor: change the address in API table for RSS services.  ES0565 device Errata sheet: - New Rev. 8 (replacing Rev. 7).  AN6014 SFSP Application Note: - New SFSP version v2.7.0 (replacing the v2.6.0).  AN2606 application Note : - New Revision 70 (replacing Rev 69). - New Bootloader version V14.5 (replacing V14.4).
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Functionality enhancement	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Improvements implemented to fix bugs.
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability ensured by ST internal tools. Die revision changes from "X" to "W" on Package Marking
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## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** STM32H562x, STM32H563x and STM32H573x - product enhancement

**PCN Reference :** EMBEDDED PROCESSING/26/15869

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H573ZIT3QTR	STM32H563ZIT3QTR	STM32H563MIY3QTR
STM32H573MIY3QTR	STM32H573IIK3QTR	STM32H563LIH3QTR
STM32H573LIH3QTR	STM32H563VGT6TR	STM32H563IIT6
STM32H563VIT6	STM32H562IGT6	STM32H563RIT7
STM32H562IGK6	STM32H562VGT6	STM32H573ZIT6TR
STM32H573ZIT3Q	STM32H562IIK6	STM32H562VIT6
STM32H563IGK7	STM32H563VGT6	STM32H573RIV6
STM32H563IGK6	STM32H563VIT7	STM32H562VGT7
STM32H563ZGT7	STM32H562IIT6	STM32H563ZGT6TR
STM32H562ZIT6	STM32H573IIK6TR	STM32H573VIT6TR
STM32H563IIK6	STM32H562ZGT6	STM32H573IIK6
STM32H573ZIT6	STM32H562AGI7	STM32H563RIT6
STM32H562RGT6	STM32H563ZIT6	STM32H563RGT6
STM32H563ZGT6	STM32H562RIT6	STM32H573LIH3Q
STM32H563LIH3Q	STM32H573VIT6	STM32H563AII3Q
STM32H563VGT7TR	STM32H573RIT6	STM32H563RGV6
STM32H562RGV6	STM32H563ZIT3Q	STM32H573ZIT7
STM32H563IIT3Q	STM32H563AII6	STM32H563VIT7TR
STM32H562VGT6TR	STM32H573VIT7	STM32H563VIT6TR
STM32H573VIT3Q	STM32H563VIT3Q	STM32H573IIT3Q
STM32H563RIV6	STM32H562AII6	STM32H562RIV6
STM32H563ZGT7TR	STM32H563IIK6TR	STM32H563IIK3Q
STM32H573AII3Q	STM32H573IIT6	STM32H562ZGT6TR
STM32H562AGI7TR	STM32H562AGI6	STM32H573AII6
STM32H563IGT6	STM32H573IIK3Q	STM32H563AGI6
STM32H562RGT6TR		

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**PRODUCT/PROCESS  
CHANGE NOTIFICATION  
PCN15869 – Additional information**

**STM32H562x, STM32H563x and STM32H573x - product  
enhancement**

**MDRF– General Purpose & Automotive Microcontrollers Division (GPAM)**

**What are the changes?**

Changes described in table below:

	Current condition	New condition
Front-End Diffusion site	ST Crolles 300 (France)	
Die revision Marking R	"X"	"W"

Example: Marking on package LQFP 100 14x14x1.4





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## How to order samples

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN15869**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

Partial Ship: 01 Price Pol: 05 Status: 01 Canc:   
%: 0 Sample Type: Sample Non Std Type  
Closing Type: Sample Std Type  
Sample Non Std Type  
Sample Non Std w Spl Tests  
Lab Sheet:

SO | NPO Sample

Header  
SO Nr: 8018582433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J  
PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:  
Notes: Status: 01 All items pending, no Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NHH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust:  
PO Item: 000001 Comm Prod: STM32F429NHH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 0000367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:   
Notes: TAN K Pieces: 0 Our Share: 0 Sample Type: Sample Non Std Type  
Project Name: Closing Date: Closing Type:

Regional Sheet: Lab Sheet:

PCN 15869



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**PCN15869  
RER2111\_STM32H5xx –  
DIE484\_W Cut 2.4  
eSTM40nm ULP  
Reliability Plan**

January 20th, 2026

GPM Quality & Reliability Department

## RERMCD2111 – Die 484 Cut 2.4 - eSTM40nm

	Test1	Method	Conditions	Test2	Method	Conditions	package	Sample x lot
Trial	HTOL	MIL-STD-883 Method 1005 JESD22A108	Ta= 125°C Vmax 3.6V (1.2V G01;3.6V GO2) 1200H	-	-		UFBGA176+25	77 x 1
	LATCH UP	0018695 JESD78	Tj = 130°C	-	-	-	UFBGA176+25	3 x 1
	ESD HBM	ANSI/JEDEC JS-001	Ta 25°C Min 1KV (Class 1C) Target 2KV (Class 2)	-	-	-	UFBGA176+25	3 x 1
	ESD CDM	ANSI/ESDA/ JEDEC JS-002	Ta 25°C Min 250V (class C1) Target 500V (Class C2a)	-	-	-	UFBGA176+25	3 x 1

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